

CONTROL OF LINER THICKNESS FOR IMPROVING
THERMAL CYCLE RELIABILITY

ABSTRACT OF THE DISCLOSURE

5 A device, system and method for evaluating reliability of a semiconductor chip are disclosed. Strain is determined at a location of interest in a structure. Failures are evaluated in a plurality of the structures after stress cycling to determine a strain threshold with
10 respect to a feature characteristic. Structures on a chip or chips are evaluated based on the feature characteristic to predict reliability based on the strain threshold and the feature characteristic. Predictions and design changes may be made based on the results.

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